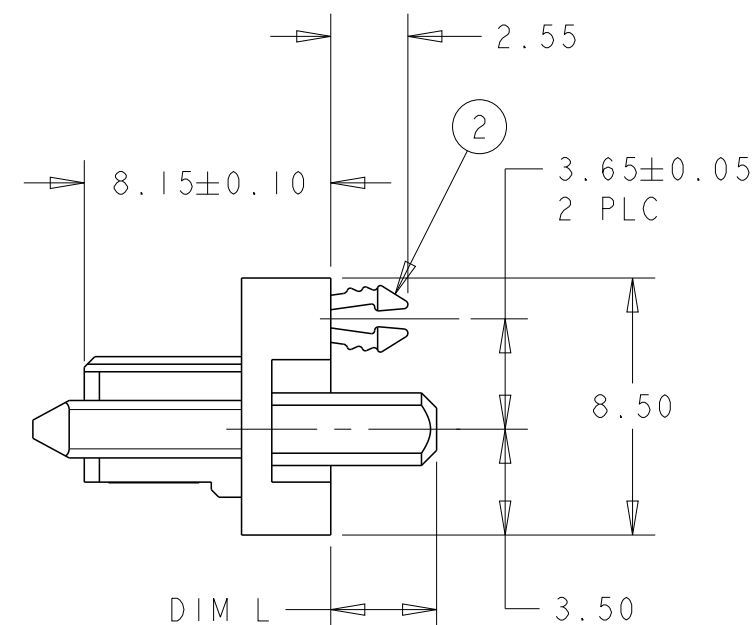




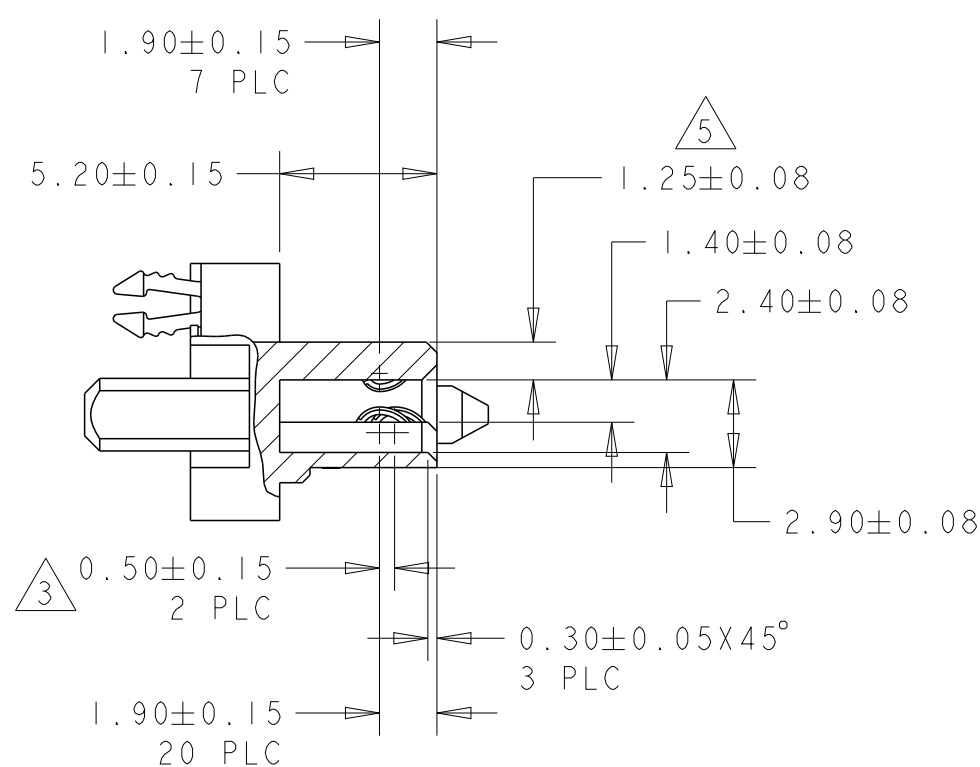
 MATERIAL:
HOUSING: HIGH TEMP THERMOPLASTIC, UL94V-0,
COLOR: BLACK
CONTACT: COPPER ALLOY
BOARDLOCK: COPPER ALLOY

△2 FINISH:
CONTACT AREA: MIN 0.76um GOLD PLATING
SOLDERTAIL: MIN 2.54um MATTE TIN PLATING
UNDERPLATE: MIN 1.27um NICKEL PLATING

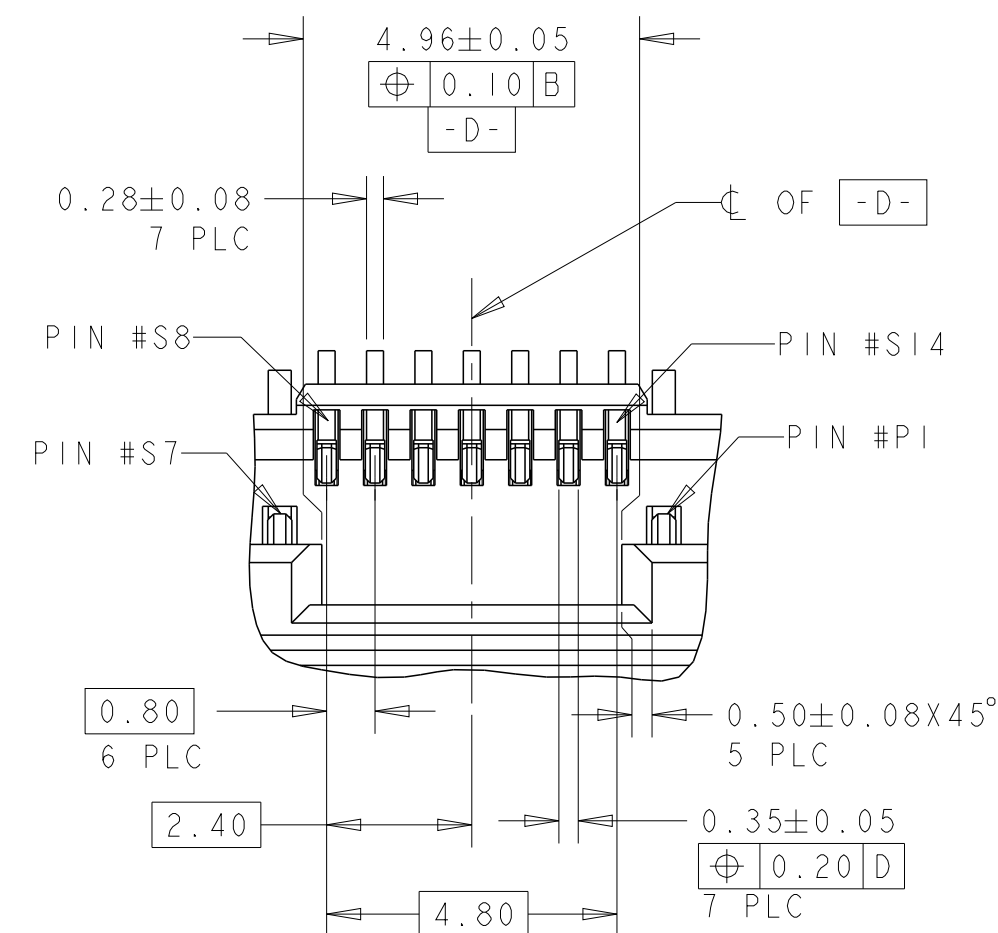
3 PIN #P4 AND #P12 ONLY

4 SOLDERTAIL TO BE 0.05 MAX ABOVE AND
0.10 MAX BELOW DATUM E

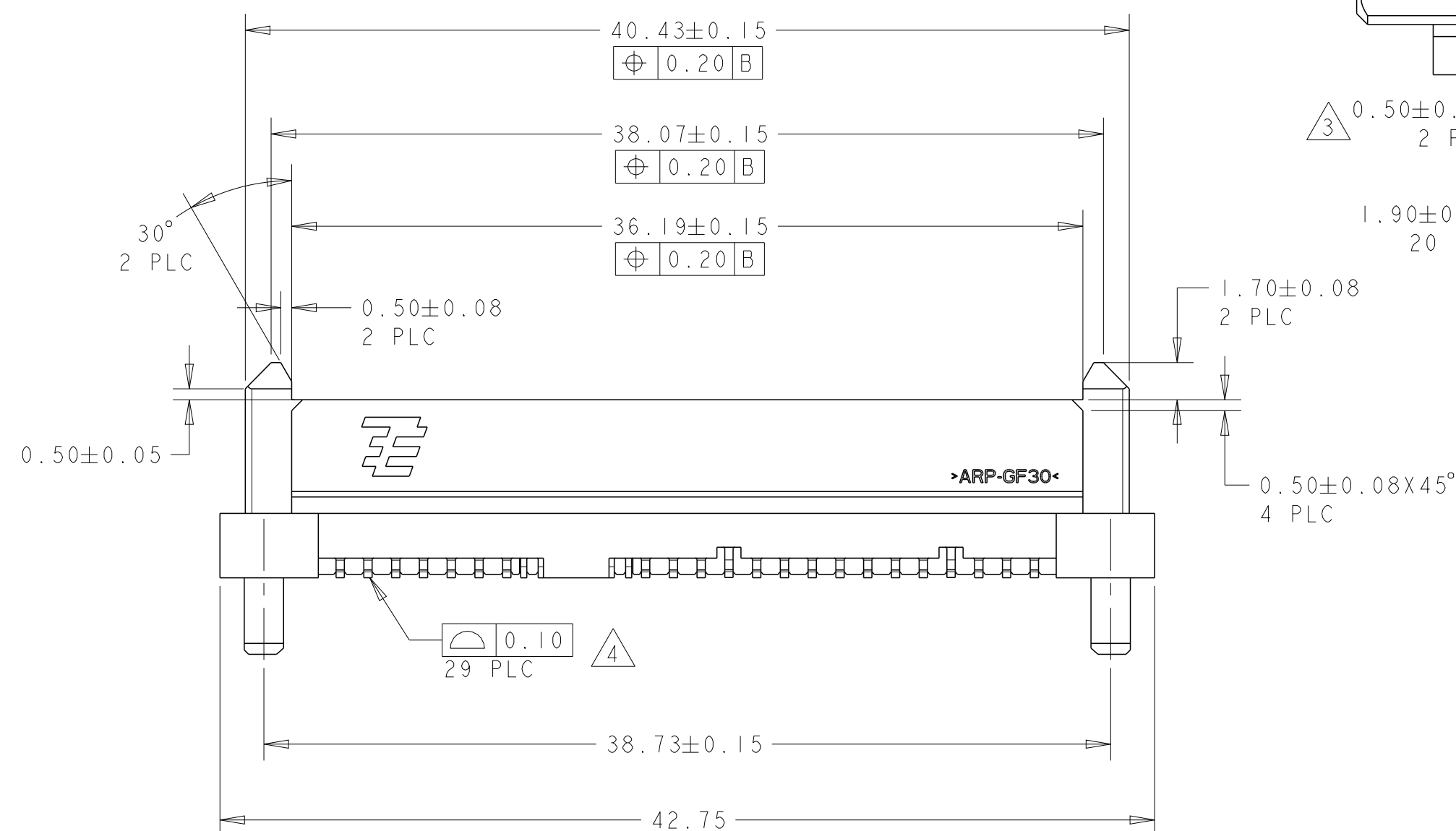
5 1.33 MAX MEASURED AT -C-



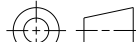
SECTION A - A



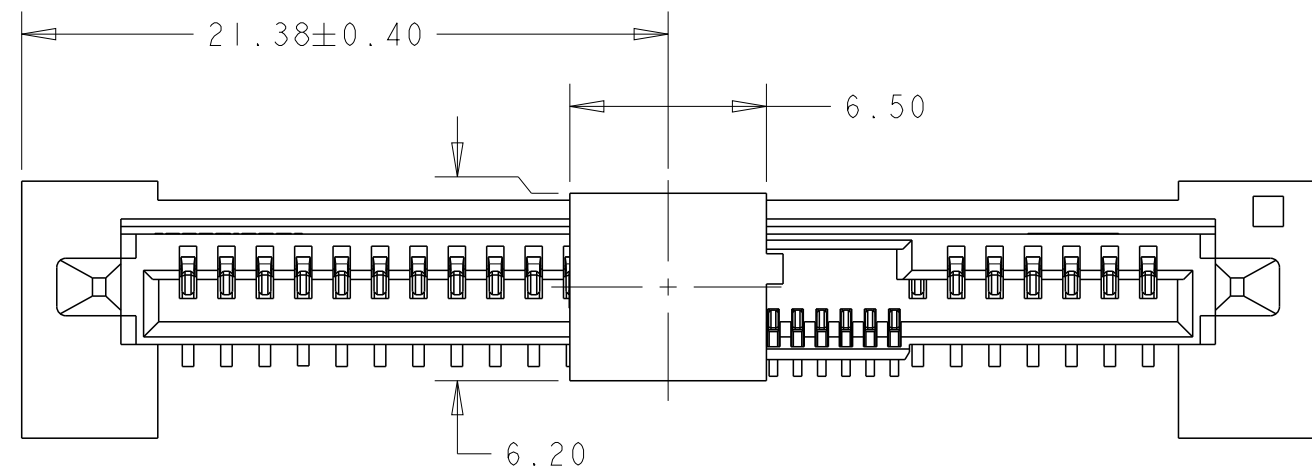
DETAIL C
SCALE 8:1



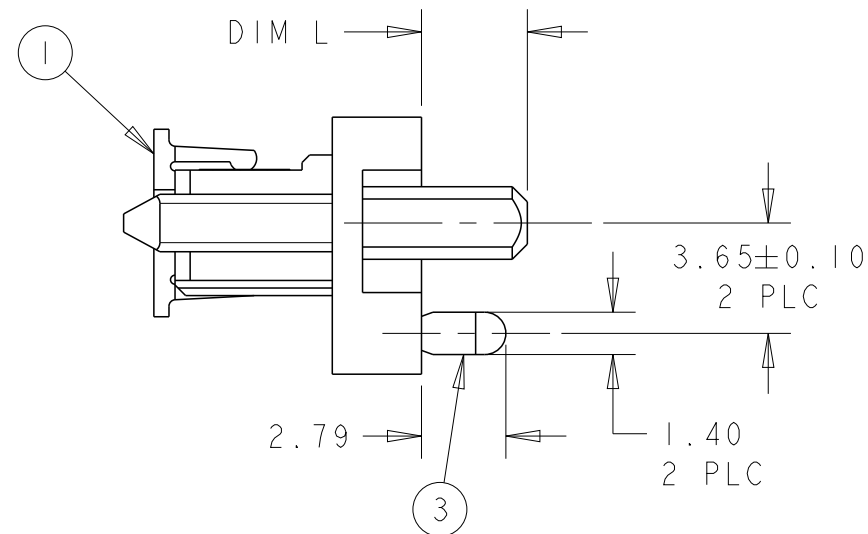
C	REVISED PER ECO-14-008474	05JUN2014	BL	JY
LTR	REVISION RECORD	DATE	DWN	APVD

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED	
mm		0 PLC	±
		1 PLC	±
		2 PLC	±0.20
		3 PLC	±
		4 PLC	±
ANGLES ± 3°			
SURFACE TEXTURE			

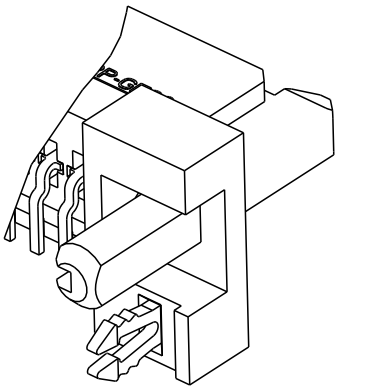
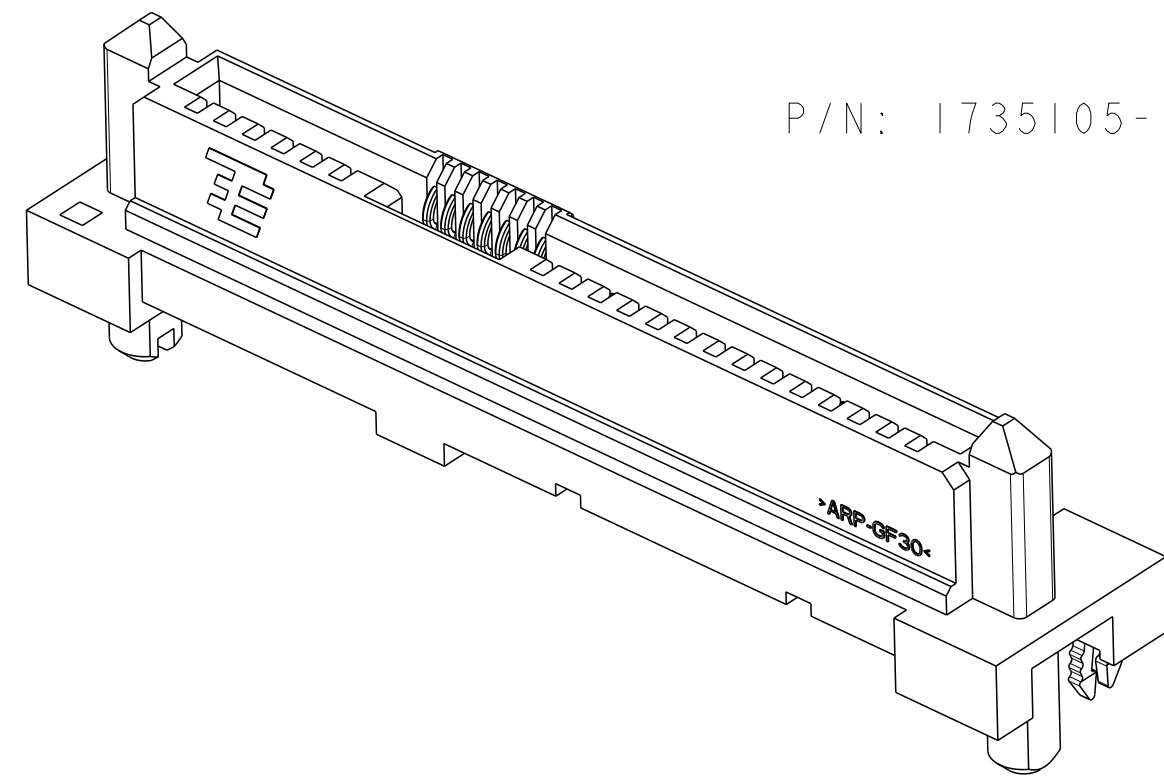
DWN	29JUL2005	MATERIAL			HEAT TREAT	-
SK LEAW						-
CHK	29JUL2005	 TE Connectivity				
SF LEONG						
APVD	29JUL2005					
SF LEONG						
NAME SAS BACKPLANE RECEPTACLE, VERTICAL, SMT						
SCALE	SIZE	DRAWING NO	SHEET		REV	
4:1	A2	1735105	1 OF 2		C	



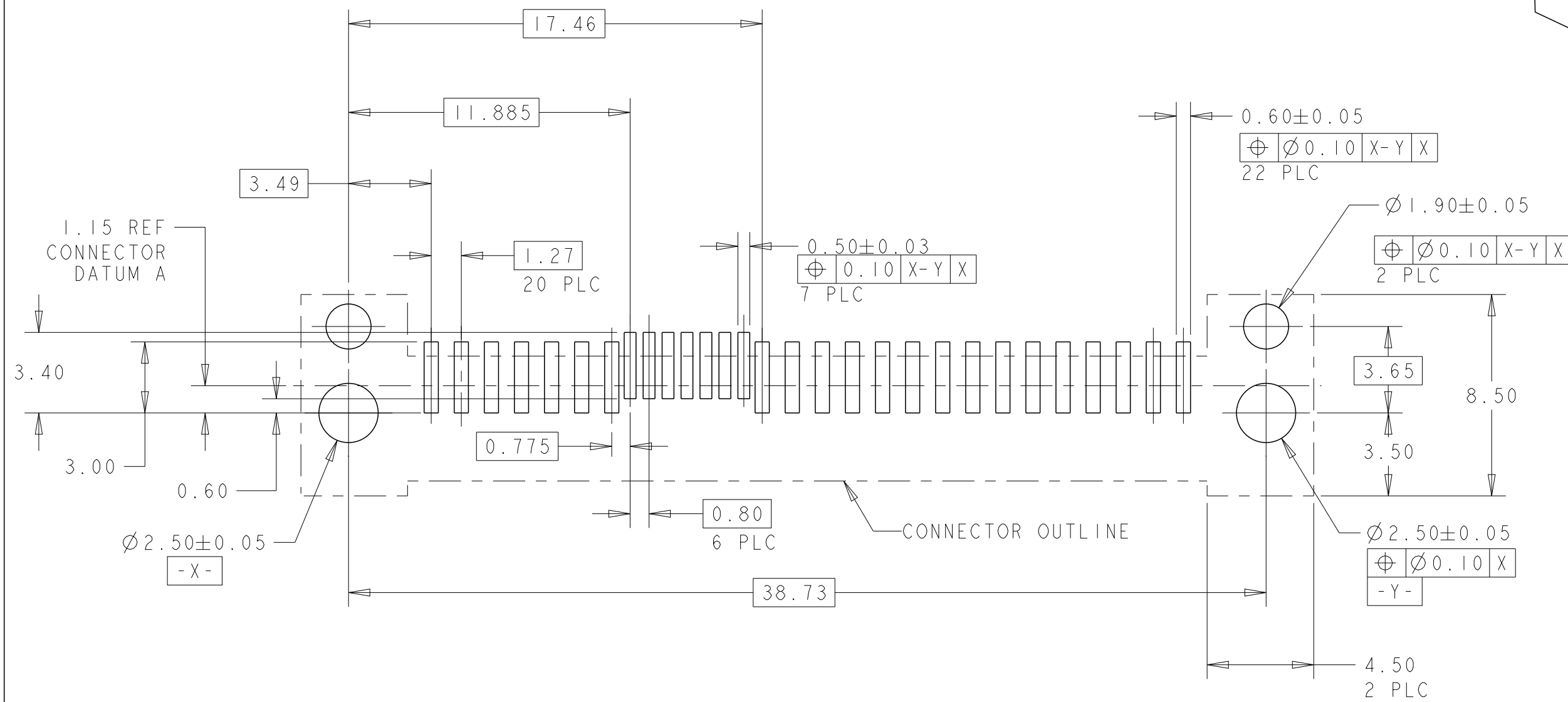
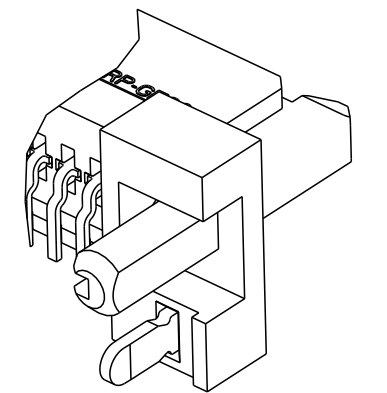
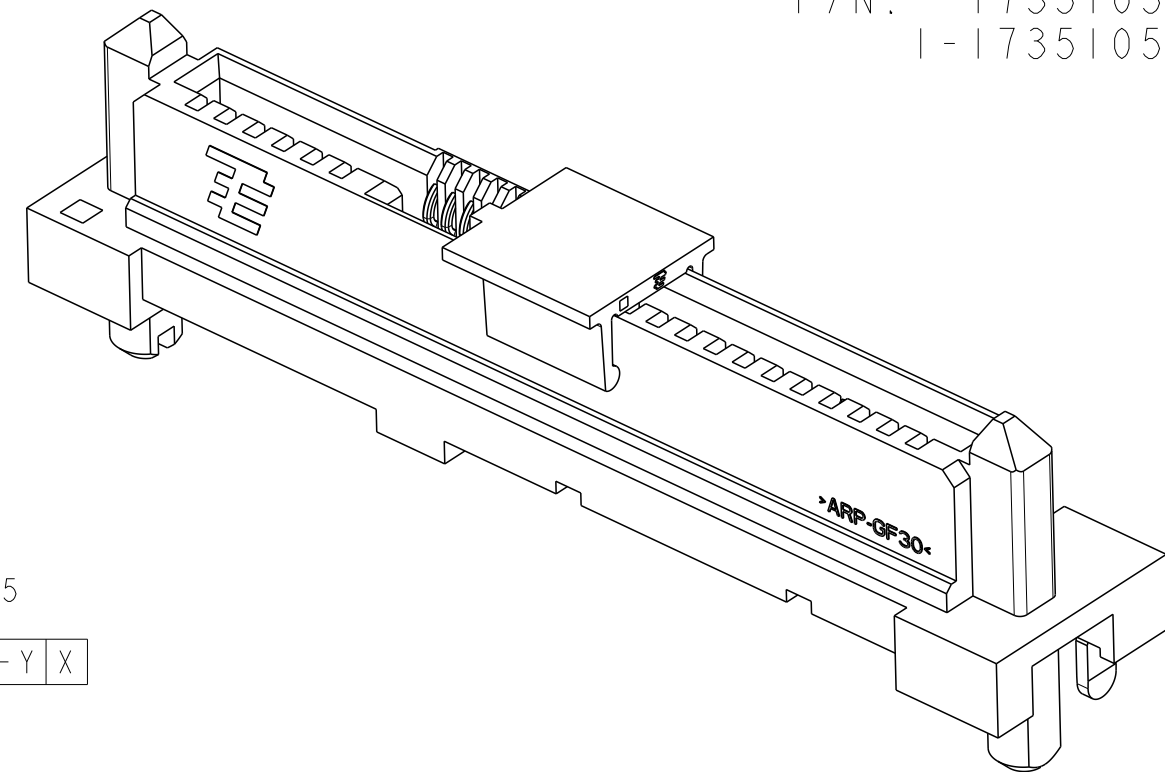
P/N: 1735105-2 AS SHOWN
1-1735105-2



P/N: 1735105-1



P/N: 1735105-2
1-1735105-2



-	SEE SHEET 1	-	-	-
LTR	REVISION RECORD	DATE	DWN	APVD

DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:
mm	0 PLC ±-
	1 PLC ±-
	2 PLC ±0.20
	3 PLC ±-
	4 PLC ±-
ANGLES: 3°	
SURFACE TEXTURE	✓

DWN	SK LEAW	29JUL2005	MATERIAL	TBD	HEAT TREAT	-
CHK	SF LEONG	29JUL2005				
APVD	SF LEONG	29JUL2005				
NAME	SAS BACKPLANE RECEPTACLE, VERTICAL, SMT					
SCALE	4:1	SIZE	A2	DRAWING NO	1735105	SHEET 2 OF 2
						REV C



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